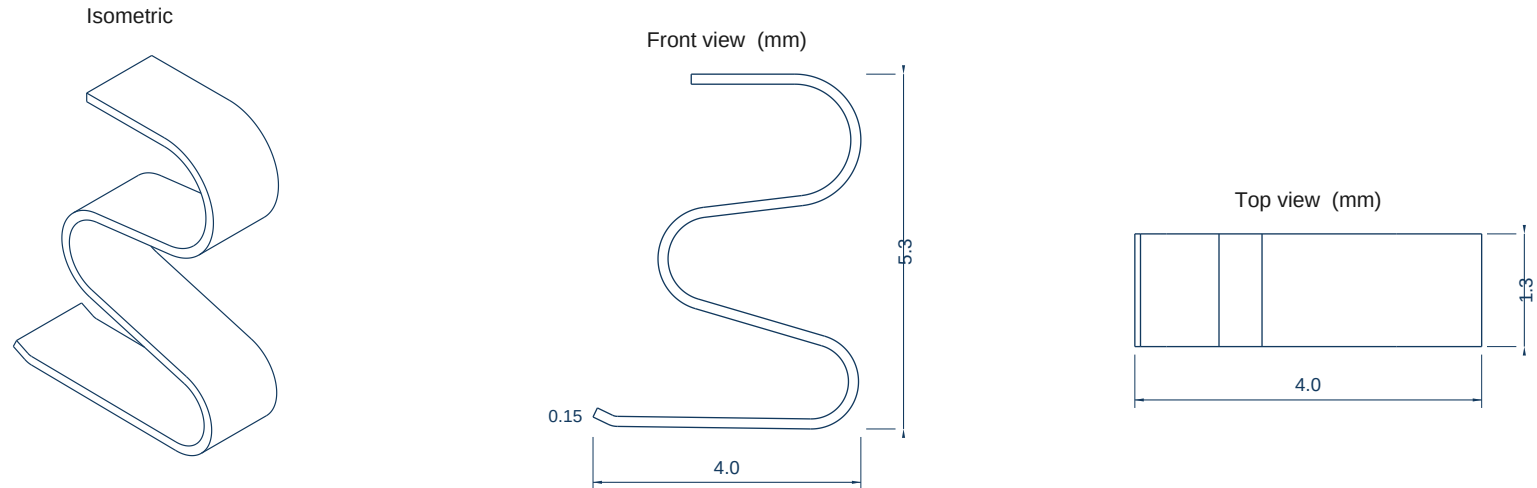




Type 3-04 B304-13040053

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.15 mm
Width	1.3 mm +/- 0.2
Length	4.0 mm +/- 0.2
Height	5.3 mm +/- 0.2
Form	S-form: top plate, 3 folds, 2 diagonal webs, base plate + lip
Bend radii	R0.910 CL, 173 deg R0.700 CL, 157 deg R0.633 CL, 164 deg
Developed length	14.71 mm
Base hole	none
Material / plating	BeCu, Gold-plated (G)
Volume / mass	2.869 mm ³ 24.0 mg (BeCu)
Product page	seyunda.com/type-3-04.html
File format	STEP AP214

PRODUCT DATA

VALUE

Mfr P/N	B304-13040053G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 4.0x1.3x5.3mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf